

EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L2	787	148/24	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/12/21 20:05
L3	1	(radiation with (detect\$5 or sens\$5)) and 148/24	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/12/21 20:05
L4	0	(((((encapsulat\$5 or acrylic) near2 resin) with (curing or cured)) same temperature) and 148/24	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/12/21 20:05
L5	1	(((((encapsulat\$5 or acrylic) near2 resin) with (curing or cured)) same temperature) and 250/208.1	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/12/21 20:06
L6	0	(((((encapsulat\$5 or acrylic) near2 resin) with (curing or cured)) same temperature) and 250/214	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/12/21 20:06
L7	2	(((((encapsulat\$5 or acrylic) near2 resin) with (curing or cured)) same temperature) and 250/239	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/12/21 20:06
L8	94	"250"/\$.ccls. and bump and encapsulat\$5	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/12/21 20:09

EAST Search History

L9	386	(encapsulat\$5 and solder and (melt\$5 or liquid\$3)).clm.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/12/21 20:11
L10	50	(encapsulat\$5 and solder and (melt\$5 or liquid\$3) and (detect\$5 or sens\$5)).clm.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/12/21 20:13
L11	55	(encapsula\$5 and solder and (melt\$5 or liquid\$3) and (detect\$5 or sens\$5)).clm.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/12/21 20:14
L12	22	(encapsula\$5 and solder and (melt\$5 or liquid\$3) and (detect\$5 or sens\$5) and temperature).clm.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/12/21 20:14
L13	0	(encapsula\$5 and solder and (melt\$5 or liquid\$3) and (detect\$5 or sens\$5) and temperature).clm. and 250/370.13	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/12/21 20:14
L14	1	(encapsula\$5 and solder and (melt\$5 or liquid\$3) and (detect\$5 or sens\$5) and temperature).clm. and "250"/\$	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/12/21 20:14
L15	0	(encapsula\$5 and solder and (melt\$5 or liquid\$3) and (detect\$5 or sens\$5) and temperature).clm. and "250"/\$.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/12/21 20:17
L16	0	(encapsula\$5 and solder and (melt\$5 or liquid\$3) and (detect\$5 or sens\$5) and temperature).clm. and "403"/\$.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/12/21 20:17

EAST Search History

L17	5	(encapsula\$5 and solder and (melt\$5 or liquid\$3) and (detect\$5 or sens\$5) and temperature).clm. and "438"/\$.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/12/21 20:18
L18	0	(encapsula\$5 and solder and (melt\$5 or liquid\$3) and (detect\$5 or sens\$5) and temperature).clm. and 250/370.13.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/12/21 20:19
S1	82	(radiation with (detect\$5 or sens\$5)) and (((encapsulat\$5 or acrylic) near2 resin) with temperature)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/12/21 17:38
S2	23	(radiation with (detect\$5 or sens\$5)) and (((encapsulat\$5 or acrylic) near2 resin) with (cured or curing)) same temperature)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/12/21 17:39
S3	0	(radiation with (detect\$5 or sens\$5)) and interposer and (solder with melat\$5 with temperature)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/12/21 17:40
S4	0	(radiation with (detect\$5 or sens\$5)) and interposer and (solder with melt\$5 with temperature)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/12/21 17:41
S5	0	(radiation with (detect\$5 or sens\$5)) and interposer and (solder with melting with temperature)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/12/21 17:41
S6	9789	(solder with melting with temperature)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/12/21 17:41

EAST Search History

S7	1189	(solder with melting with temperature) and encapsulat\$5	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/12/21 17:41
S8	7	((solder with melting with temperature) and encapsulat\$5) and "250"/\$.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/12/21 17:49
S9	5396	solder with reflow with temperature	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/12/21 17:50
S10	231	S9 and (encapsulat\$5 with temperature)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/12/21 17:50
S11	0	S9 and (encapsulat\$5 with temperature) and "250"/\$.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/12/21 17:51
S13	302	250/370.13	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/12/21 17:51
S14	34	250/370.13 and solder	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/12/21 17:51
S15	0	250/370.13 and solder and encapsulat\$5	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/12/21 17:52

EAST Search History

S17	2	250/370.13 and solder and encapsulat\$5	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/12/21 17:53
S18	212	"250"/\$.ccls. and solder and encapsulat\$5	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/12/21 20:09
S19	4	"5952646".pn. "6017634".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/12/21 17:55